

<p style="text-align: center;"><b>O I P E</b>  <b>LIST OF REFERENCES CITED BY APPLICANT</b>  <b>NOV 21 2001</b> (Use several sheets if necessary)</p> <p style="text-align: right;">RECEIVED U.S. PATENT &amp; TRADEMARK OFFICE</p>					ATTY. DOCKET NO. <b>9818-0055-999</b>	APPLICATION NO. <b>09/938,075</b>	
					APPLICANT <b>Mohammad Eslamy</b>		
					FILING DATE <b>August 23, 2001</b>	GROUP <b>2811</b>	
<b>U.S. PATENT DOCUMENTS</b>							
*EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
	AA						
	AB						
	AC						
	AD						
	AE						
	AF						
	AG						
	AH						
	AI						
<b>FOREIGN PATENT DOCUMENTS</b>							
		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION
	AJ						YES      NO
	AK						
	AL						
	AM						
	AN						
<b>OTHER REFERENCES (Including Author, Title, Date, Pertinent Pages, Etc.)</b>							
JN	AO	R. Tummala <i>et al.</i> , MICROELECTRONICS PACKAGING HANDBOOK, PART II, SEMICONDUCTOR PACKAGING, (Second Edition, 1997) pp. 78-81, 165-169 and 305-311.					
	AP						
	AQ						
EXAMINER	JOSEPH NEUREN			DATE CONSIDERED	3/7/02		

\*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.